

*B1*

21. (Amended) An integrated circuit having at least one trench capacitor, said trench capacitor comprising:

3           a substrate;

4           an opening in said substrate, said opening having vertical sides, said vertical sides

5           including a plurality of lateral openings, wherein said lateral openings comprise rectangular

6           openings in cross-section;

7           an insulator lining said opening; and

8           a conductor filling said opening.

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**Please cancel claims 22-24 without prejudice or disclaimer.**

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**Please add the following new claims:**

*B2*

27. An integrated circuit structure comprising:

2           a substrate;

3           an opening in said substrate, said opening having vertical sides, said vertical sides

4           including a plurality of lateral openings, wherein said lateral openings comprise V-shaped

5           openings in cross-section; and

6           a conductor filling said opening.

*B2*  
*cont*

1 28. The integrated circuit in claim 27, wherein said lateral openings increase a surface area of  
2 said structure.

1 29. The integrated circuit in claim 27, wherein said lateral openings increase a capacitance of  
2 said structure.

1 30. An integrated circuit structure comprising:  
2 a substrate;  
3 an opening in said substrate, said opening comprising a first rectangular portion and a  
4 second rectangular portion, wherein said second rectangular portion has larger dimensions than  
5 said first rectangular portion; and  
6 a conductor filling said opening.

1 31. The integrated circuit in claim 30, wherein said second rectangular portion is deeper in  
2 said opening than said first rectangular portion.

1 32. The integrated circuit in claim 30, wherein said first rectangular portion is deeper in said  
2 opening than said second rectangular portion.

1 33. The integrated circuit in claim 30, wherein said lateral openings increase a surface area of  
2 said trench capacitor.

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*Claim*

34. The integrated circuit in claim 30, wherein said lateral openings increase a capacitance of said structure.

1 35. An integrated circuit structure comprising:

2 a substrate;

3 an opening in said substrate, said opening comprising a first rectangular portion, a second  
4 rectangular portion, and a third rectangular portion, wherein said second rectangular portion has  
5 larger dimensions than said first rectangular portion and said third rectangular portion; and  
6 a conductor filling said opening.

1 36. The integrated circuit in claim 35, wherein said second rectangular portion is between  
2 said first rectangular portion and said third rectangular portion.

1 37. The integrated circuit in claim 35, wherein said first rectangular portion and said third  
2 rectangular portion have substantially similar dimensions.

1 38. The integrated circuit in claim 35, wherein said lateral openings increase a surface area of  
2 said structure.

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